

## Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	<b>Company Unique ID</b> 00-489-5751	<b>Unique ID Authority</b> Dun & Bradstreet	<b>Response Date*</b> Sat, May 19, 2012 03:47 AM
<b>Contact Name *</b> David Lancaster	<b>Title - Contact</b> Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	<b>Title - Representative</b> Product Ecology	<b>Phone - Representative *</b> 801-562-7455	<b>Email - Representative *</b> david.lancaster@fairchildsemi.com

Requester Item Number	Mf Item Number	Mf Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
FSA2367BQX	FSA2367BQX	14-MLP DQFN 2.5X3			INTERNAL PENANG	0.017	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Nickel/Palladium/Gold (Ni/Pd/Au)	CU Alloy	1	260 C	30 seconds	3

\* Required Field

<b>RoHS Material Composition Declaration</b>	<b>Declaration Type * Custom</b>
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<b>RoHS Directive 2002/95/EC</b>	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

<b>RoHS Declaration *</b>	<b>1 - Item(s) does not contain RoHS restricted substances per the definition above</b>	<b>Supplier Acceptance * Accepted</b>
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**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC	0
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**Declaration Signature**

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name 14-MLP DQFN 2.5X3

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.115	Supplier		Silicon	0.115	7440-21-3	6667
Die Attach	Other Organic Materials	0.058	Supplier		Acrylic Resin	0.009	54208-63-8	508
			Supplier		Silver	0.050	7440-22-4	2876
Encapsulation	Thermoplastics	10.200	Supplier		Carbon Black	0.102	1333-86-4	5913
			Supplier		Epoxy Resin	1.020	29690-82-2	59134
			Supplier		Silica, vitreous	9.078	60676-86-0	526294
Lead Frame	Copper & its alloys	6.460	Supplier		Chromium	0.019	7440-47-3	1125
			Supplier		Copper	6.420	7440-50-8	372198
			Supplier		Tin	0.016	7440-31-5	939
			Supplier		Zinc	0.006	7440-66-6	375
Terminal Finish	Precious metals	0.066	Supplier		Gold	0.001	7440-57-5	55
			B	Nickel (external applications only)	Nickel	0.059	7440-02-0	3397
			Supplier		Palladium	0.006	7440-05-3	344
Wire Bond	Precious metals	0.348	Supplier		Gold	0.348	7440-57-5	20175